

## SEM Imaging of Films of Metal Nanoparticles Deposited on Semiconductors

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Layers of metal nanoparticles on semiconductor surfaces show interesting effects which may be desirable for practical applications. Association of metal nanoparticles with semiconductor materials opens up novel means to gain structures with remarkable properties.

Schottky barriers with layers of nanosized metal particles on semiconductor wafers can be used as hydrogen sensors which are more sensitive than those prepared by conventional deposition techniques.

Colloids of metal nanoparticles stabilized by AOT reverse micelles in isooctane were prepared. The colloids contain nanoparticles with the size distribution of 5-10 nm in diameter. Nanolayers were deposited by electrophoresis onto semiconductor wafers.

The morphology of the deposited layers was observed by JEOL JSM 7500F scanning microscope.

We discuss the influence of:

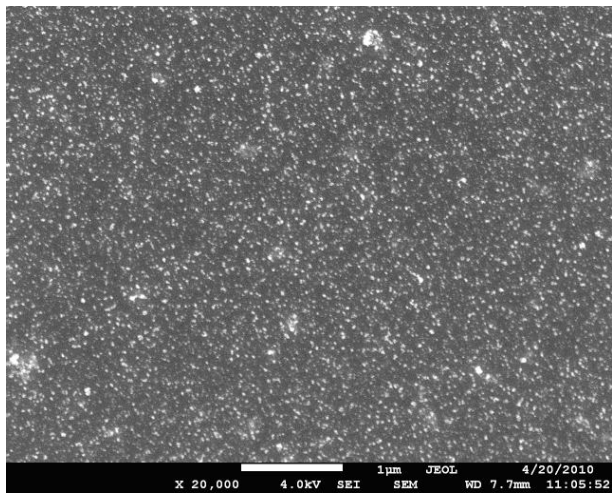
- conditions of the electrophoretic deposition, i.e. electrode polarity, time of the deposition and applied voltage,
- the post-deposition treatment, i.e. thermal annealing,
- the properties of deposited colloids

This work has been supported by the Czech Ministry of Education, Youth and Sports in the framework of the Research Plan 60840770022 and by the Grant Agency of the Academy of Science of the Czech Republic, project KAN401220801 and the Czech Science Foundation grant 102/09/1037.

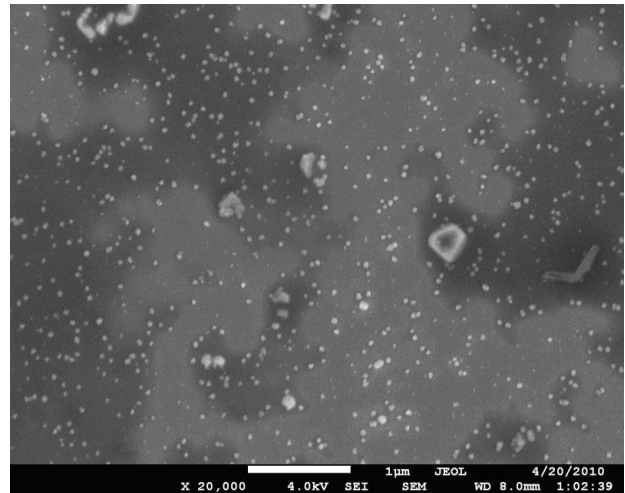
### References

- [1] CHEN D.H.; WANG Ch.Ch.; HUANG T.Ch. *Preparation of Palladium Ultrafine Particles in Reverse Micelles*. **Journal of Colloid and Interface Science**, 1999, č. 210, s. 123-129. ISSN 0021-9797/99
- [2] Žďánský K., Zavadil J., Kacerovský P., Lorinčík J., Vaniš J., Kostka F., Černohorský O., Fojtík A., Reboun J., Čermák J.: *Electrophoresis deposition of metal nanoparticles with reverse micelles onto InP*, **International Journal of Materials Research**, 2009, vol. 9., p. 1234-1238, ISSN 1862-5282.

**Figures:**

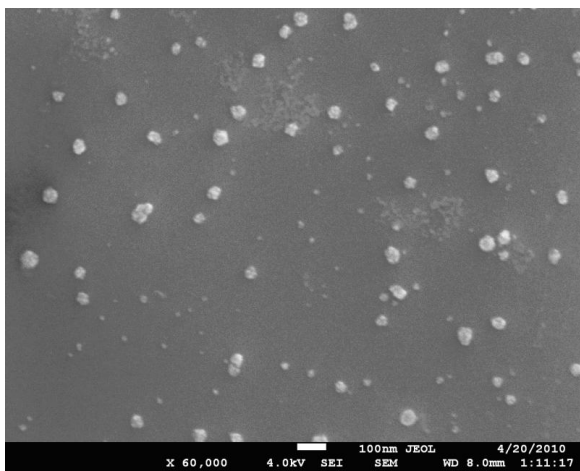


a) applied voltage - 100V

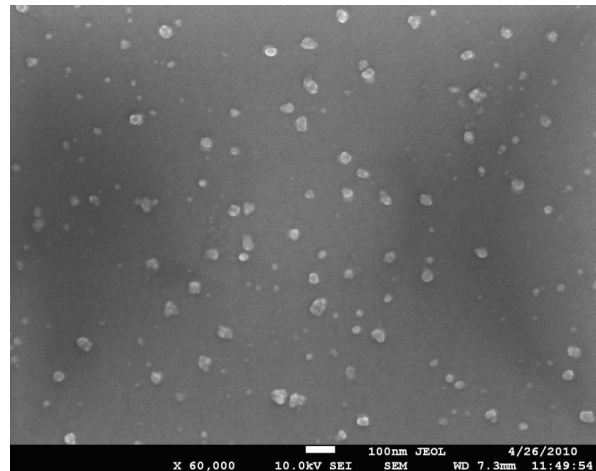


b) applied voltage - 30V

**Fig. 1:** Comparison morphology – dependence on applied voltage



a) non-annealed sample



b) annealed sample

**Fig. 2:** Comparison morphology – dependence on annealing